Overview

HP EliteBook 745 G6 Notebook PC



- 1. HD and IR Camera (Optional)
- 2. Ambient Light Sensor (Optional)
- 3. IR Camera LEDs (Optional)
- 4. Internal Microphones
- 5. HP Privacy Camera Shutter
- 6. HD Camera LED

Left

- 7. Clickpad
- 8. Smartcard Reader (Optional)
- 9. USB 3.1 Gen 1 Charging Port
- 10. Vents
- 11. Security Lock Slot (Lock sold separately)
- 12. Power Button

Overview



- 1. Power Connector
- 2. USB Type-C™
- 3. Docking Connector
- 4. Ethernet Port
- 5. HDMI Port (Cable not included)

Right

- 6. USB 3.1 Gen 1 Port
- 7. Audio Combo Jack
- 8. SIM Card Slot1
- 9. Touch Fingerprint Sensor (Optional)
- 10. Pointstick

1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

Overview

AT A GLANCE

- Eye-catching Ultraslim design, premium precision-crafted machined aluminum (CNC), seamless formed aluminum chassis for clean, crisp, premium look and feel
- Choice of 2nd Generation AMD Ryzen™ PRO processors
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new Thunderbolt™ dock¹
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ant-glare touch displays with ambient light sensor
- Choice of displays:
 - 35.6 cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 250 cd/m², 45% NTSC 35.6 cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 400 cd/m², 72% NTSC 35.6cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 1000 cd/m², 72% NTSC with HP Sure View 35.6cm (14.0") diagonal FHD IPS Anti-Glare On-Cell LED-backlit touch, 250 cd/m², 45% NTSC
- Enterprise grade security with HP SureStart, HP Privacy Camera¹, HP Sure View⁴, HP Sure Run, HP Sure Recover, HP Sure Click, HP Sure Sense⁵, SmartCard Reader¹ and Touch Fingerprint reader¹
- Preinstalled with Windows 10 versions or FreeDOS
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles²
- Flexible wireless connectivity options
- Passed MIL-STD 810G tests³
- 1. Sold separately or as an optional feature.
- 2. HP Elite notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 3. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 4. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape. Available in Q3' 19.
- 5. HP Sure Sense requires Windows 10. See product specifications for availability.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

PRODUCT NAME

HP EliteBook 745 G6 Notebook PC

OPERATING SYSTEM

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro 64 (National Academic License)²

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

AMD Ryzen™ 7 PRO 3700U APU with Radeon™ Vega 10 Graphics (2.3 GHz base clock, up to 4 GHz max boost clock, 4 MB L3 cache. 4 cores)^{3,4,5}

AMD Ryzen™ 5 PRO 3500U APU with Radeon™ Vega 8 Graphics (2.1 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5}

AMD Ryzen™ 3 PRO 3300U APU with Radeon™ Vega 6 Graphics (2.1 GHz base clock, up to 3.5 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5}

Processor Family

2nd Generation AMD® Ryzen™ PRO APU processor6

- 3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
- 5. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor



Features

GRAPHICS

Integrated

AMD Radeon™ Vega Graphics⁷

Supports

Support HD decode, DX12, and HDMI 2.0

7. HD content required to view HD images.

DISPLAY

Non-Touch

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)^{7, 9,10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera (1920 x 1080)^{7, 9,10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera (1920 x 1080)^{7, 9,10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC for WWAN (1920 x 1080)^{7,9,10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera for WWAN (1920 \times 1080)^{7, 9,10}

35.6 cm (14") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera for WWAN (1920 \times 1080) 7,9,10

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD+IR camera $(1920 \times 1080)^{7,9,10}$

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080) 7,9,10

35.6 cm (14") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 1000 nits with HP Sure View G3 Integrated Privacy Screen, 72% NTSC, with Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080)^{7, 8, 9,10}

Touch

35.56 cm (14") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC with HD+IR camera (1920 x 1080)^{7, 9,10}

35.56 cm (14") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC with HD+IR camera for WWAN $(1920 \times 1080)^{7,9,10}$

HDMI 2.0

Support resolution up to 4k @ 60Hz

- 7. HD content required to view HD images.
- 8. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation. Available in Q3' 19.
- 9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 10. Sold separately or as an optional feature



Features

Docking station model	Total number of supported displays (incl. the notebook display)	Max.resolutions supported	Dock Connectors	Technical limitations
HP UltraSlim Docking Station	4	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays into DP
HP Thunderbolt Dock G2	4	Dual 2560 x 1600 @ 60Hz Single 3840 x 2160 @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	
HP Elite USB-C Dock G4	4	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary M.2 Storage

128 GB SATA-3 SS TLC¹¹
256 GB PCIe® NVMe™ Value SS TLC¹¹
256 GB PCIe® Gen3x4 NVMe™ SS TLC¹¹
256 GB SATA-3 TLC Opal 2¹¹
512 GB PCIe® Gen3x4 NVMe™ SS TLC¹¹
512 GB PCIe® Gen3x4 NVMe™ SS TLC Opal 2¹¹
512 GB PCIe® Value¹¹

1 TB PCIe® Gen3 x4 NVMe™ SS TLC11

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

32 GB DDR4-2400 SDRAM

Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)¹²
16 GB DDR4-2400 SDRAM (1 X 16 GB)¹²
16 GB DDR4-2400 SDRAM (2 X 8 GB)¹²
8 GB DDR4-2400 SDRAM (1 x 8 GB)¹²
8 GB DDR4-2400 SDRAM (2 x 4 GB)¹²
4 GB DDR4-2400 SDRAM (1 x 4 GB)¹²

Memory Slots

2 SODIMM
Both slots are customer accessible / upgradeable
DDR4 SODIMMS, system runs at 2400



Features

Supports Dual Channel Memory

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AC 9260 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™13 Intel® AX200 Wi-Fi 6¹¹ (2x2) and Bluetooth® 5 Combo, non-vPro™ (supporting gigabit file transfer speeds) Realtek RTL8822BE 802.11ac (2x2) and Bluetooth® 4.2 Combo¹³

WWAN

Intel® XMM™ 7360 LTE-Advanced Cat 914

NFC

NXP NPC300 Near Field Communication Module

Miracast

Native Miracast Support15

Ethernet

Realtek PCIe GbE Family Controller 10/100/1000¹⁶

- 13. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
- 14. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 15. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 16. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.
- 17. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 2 Integrated Stereo Speakers

Camera

720p HD camera^{7,10} 720p HD+IR camera^{7,10,18}

Sensors



Features

Ambient light sensor (Select models only)
Hall Sensor

- 7. HD content required to view HD images.
- 10. Sold separately or as an optional feature.
- 18. Internet access required.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Collaboration Keyboard, spill resistant with drain Backlit keyboard available as an option

Pointing Device

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

- F1 Display Switching
- F2 Blank or Privacy
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 numlk
- F11 Wireless
- F12 Calendar
- Share/Present
- Call Answer
- Call End

Hidden Function Keys

- Fn+R Break
- Fn+S Sys Rq
- Fn+C Scroll Lock
- Fn+E Insert
- Fn +W Pause



Features

SOFTWARE AND SECURITY

Preinstalled Software BIOS

HP BIOSphere Gen5¹⁹

HP Drive Lock & Automatic Drive Lock²⁰

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²¹

Absolute Persistence Module²²

Pre-boot Authentication

Software

HP Native Miracast Support²³

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStart

HP Support Assistant²⁴

HP Noise Cancellation Software

Buy Office (sold separately)

Manageability Features

HP Driver Packs²⁵

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3²⁶

HP Cloud Recovery²⁷

Client Security Software

HP Client Security Manager Gen5²⁸

HP Fingerprint Sensor²⁹

HP Power On Authentication

Windows Defender³⁰

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³¹

SATA 0,1 port disablement (via BIOS)

USB enable/disable (via BIOS)

Power-on password (via BIOS)



Features

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Click³²

HP Sure Start For AMD³³

Sure Run Gen234

Sure Recover Gen235

Sure Sense³⁶

Security

TPM

Model: Infineon SLB9670

Version: 7.85 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes (select models only)

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Certification:

Yes/No

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

Graphics (Intel Video Driver): TBD

WWAN: TBD WLAN: TBD

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

19. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

20. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

- 21. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 22. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 23. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.



Features

- 24. HP Support Assistant requires Windows and Internet access.
- 25. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 26. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 27. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 28. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 29. HP Fingerprint Sensor sold separately or as an optional feature.
- 30. Windows Defender Opt in and internet connection required for updates.
- 31. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).re TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 32. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 33. HP Sure Start for AMD is available on select HP PCs with AMD processors. See product specifications for availability.
- 34. HP Sure Run Gen2: See product specifications for availability.
- 35. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel® Optane™. 36. HP Sure Sense requires Windows 10. See product specifications for availability.



Features

POWER

Power Supply

HP Smart 45 W External AC power adapter³⁷
HP Smart 45 W External AC power adapter, 2-prong (Japan only)³⁷
HP Smart 65 W External AC power adapter³⁷
HP Smart 65 W EM External AC power adapter³⁷
45 W USB Type-C™ adapter³⁷
65 W USB Type-C™ adapter³⁷

Primary Battery

HP Long Life 3-cell, 50 Wh Li-ion^{38,39} Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)^{38,39}

Battery Life

TBD⁴⁰

Power Cord

2-wire plug - 1.0m³⁷
3-wire plug - 1.0m³⁷
3-wire plug - 1.8m³⁷
Duckhead power cord - 1.0m³⁷
Duckhead power cord - 1.8m³⁷

- 37. Availability may vary by country.
- 38. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 39. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 40. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 3.31 lbs (non-touch); Starting at 3.33 lbs (touch)⁴¹ Starting at 1.50 kg (non-touch); Starting at 1.51 kg (touch)⁴¹

Product Dimensions (w x d x h)

Non-Touch

12.84 x 9.22 x 0.7 in 32.6 x 23.43 x 1.79 cm

Touch

12.84 x 9.22 x 0.71 in 32.6 x 23.43 x 1.81 cm

41. Weight will vary by configuration.

PORTS/SLOTS



Features

Ports

1 USB Type-C[™] (Alt Mode) 2 USB 3.1 Gen 1 (1 charging) 1 HDMI 2.0⁴²

1 HUMI 2.0 -

1 RJ-45 / Ethernet

1 Docking connector

1 Headphone/microphone combo

1 AC power

1 SIM card slot16

1 Smartcard reader16

16. Sold as an optional feature.

42. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year or 3- year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁴³

43. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

SYSTEM UNIT

Stand-Alone Power **Nominal Operating** 19V

Voltage **Requirements (AC Power)**

> **Average Operating Power** Win 10

Integrated Graphics AMD has no this data (APU is 15W)

Max Operating Power IJMA < 45W

32° to 95° F (0° to 35° C) **Temperature** Operating

> Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity Operating 10% to 90%, non-condensing

> 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature Non-operating

Shock **Operating** 40 G, 2 ms, half-sine

> 200 G, 2 ms, half-sine Non-operating

Random Vibration Operating 0.75 grms

> Non-operating 1.50 grms

Altitude (unpressurized) **Operating** -50 to 10,000 ft (-15.24 to 3,048 m)

> Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard

Certifications

UL Yes **CSA** Yes **FCC Compliance** Yes

ENERGY STAR® Yes. Select models 44 **EPEAT® 2019** Yes. Silver in U.S.45

Australia / Yes

NZ A-Tick Compliance

Yes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes Yes Saudi Arabian Compliance Yes (ICCP)

UKRSERTCOMPUTER Yes



^{44.} Configurations of the HP Elitebook 745 G6 that are ENERGY STAR® certified are identified as HP Elitebook 745 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.

^{45.} Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

Technical Specifications

ENVIRONMENTAL & INDUSTRY

Environmental Data	Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT® Silver registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified Edge • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label*			
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".			
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
	Normal Operation (Sort idle)	5.77 W	5.77 W	5.04 W	
	Normal Operation (Long idle)	4.45 W	3.37 W	4.52 W	
	Sleep	0.62 W	0.89 W	0.66 W	
	Off	0.44 W	0.36 W	0.49 W	
		within the model family. For compliant with the applications for STAR® compliant configura	HP computers marked with ble U.S. Environmental Prot computers. If a model fan ations, then energy efficiend hard disk drive, a high eff	compliant product if offered the ENERGY STAR® Logo are section Agency (EPA) ENERG nily does not offer ENERG cy data listed is for a typicall iciency power supply, and a	

Technical Specifications

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	19.73 BTU/hr	19.73 BTU/hr	17.24 BTU/hr	
Normal Operation (Long idle)	15.22 BTU/hr	11.53 BTU/hr	15.46 BTU/hr	
Sleep	2.12 BTU/hr	3.04 BTU/hr	2.26 BTU/hr	
Off	1.50 BTU/hr	1.23 BTU/hr	1.68 BTU/hr	
	*NOTE: Heat dissipation is service level is attained fo		ne measured watts, assuming tl	
Declared Noise	Sound Power		Sound Pressure	
Emissions (in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{pAm} , decibels)	
Typically Configured — Idle	2.5		14.5	
Fixed Disk – Random writes	3.2		27.1	
Optical Drive – Sequential reads	3.3		28.7	
Longevity and Upgrading			g its useful life by several years ined in the product may include	
	 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking station 1 multi-bay II storage port Interchangeable HDD?? 			
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries	This battery(s) in this prod	uct comply with EU Dir	ective 2006/66/EC	
	Batteries used in the produ	uct do not contain:		



Technical Specifications

		Cadmium	greater than 20nnm by weight		
		Cadmium greater than 20ppm by weight Battery description: CR2032 (coin cell) / SS03050 Battery type: Lithium / Li-Ion/Li-Ion Polymer Battery description: 6-cell high capacity Lithium-Ion battery (optional 8 cell available) Battery type:			
	Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Silver level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. This product contains 5.69% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1. This product is 96.4% recycle-able when properly disposed of at end of life. 			
Ī	Packaging Materials	External:	PAPER/Corrugated	41 g	
		Internal:	PLASTIC/EPE (Expanded Polyethylene)	68 g	
			PLASTIC/Polyethylene low density - LDPE	14 g	
		PLASTIC/Polypropylene - PP 4 g			
			packaging material contains at least 0.8% recycled content ted paper packaging materials contains at least 0.4% recy		
	RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement. This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_spe			
	Material Usage			ronment at	



Technical Specifications

	cifications.html):
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl (Ethers (PBBEs) Polybrominated Biphenyl (PCB) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office.

Technical Specifications

Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp- information/environment/ecolabels.html ISO 14001 certificates:
http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755 842
and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

DISPLAYS

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim NB

Outline Dimensions (W x H) 316.17 x 197.98 mm (max)

Active Area 309.37 x 174.02 mm (typ.)

Weight 285 g (max)

Diagonal Size 14.0 inch

Thickness 3.0 mm (max)

Interface eDP 1.2 (2 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 600:1 (typ.)

Refresh Rate 60 Hz
Brightness 250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 45%
Color Depth 6 bits

Viewing Angle UWVA 85/85/85



Technical Specifications

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim Touch on Panel Narrow Bezel

Outline Dimensions (W x H) 316.112 x 197.98 mm (max) **Active Area** 309.37 x 174.02 mm (typ.)

Weight 290 g (max)
Diagonal Size 14.0 inch

Thickness 3.0 mm (panel side) / 3.2 mm (PCBA Side) (max)

Interface eDP 1.2

Surface Treatment Anti-Glare On-cell

Touch Enabled Yes

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 45%
Color Depth 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 400 nits eDP 1.3+PSR slim **Outline Dimensions (W x H)** 316.11 x 197.98 mm (max)

 Active Area
 309.31 x 173.99 mm

 Weight
 <285 g (max)</td>

Diagonal Size14.0 inchThickness3.0 mm (max)

Interface eDP 1.3 + PSR (2 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness400 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Backlight LED Color Gamut Coverage 72%

Color Depth 6 bits + Hi FRC
Viewing Angle UWVA 85/85/85/85

Technical Specifications

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72 percent cg 1000 nits eDP 1.4+PSR2 flat Privacy Narrow Bezel*
 Outline Dimensions (W x H)
 315.31 x 195.498 mm (max)

 Active Area
 309.312 x 173.988 mm (typ.)

Weight265 g (max)Diagonal Size14.0 inchThickness3.0 mm (max)

Interface eDP 1.4 + PSR2 (4 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 2000:1 (typ.)

Refresh Rate60 HzBrightness1000 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 72%
Color Depth 8 bits

Viewing Angle UWVA 85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



^{*} Available in Q3'19.

Technical Specifications

STORAGE

SSD 128 GB 2280 M2 SATA-3 TLC Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 ATA-8, SATA 3.0

Maximum Sequential Read Around 540 ~ 560 MB/s
Maximum Sequential Write Around 380 ~ 530 MB/s

Logical Blocks 250069680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; DIPM; TRIM; DEVSLP

SSD 1 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided

Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 3200 ~ 3480 MB/s
Maximum Sequential Write Around 2400 ~ 3037 MB/s

Logical Blocks 2000409264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 256 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 2900 ~ 3167 MB/s
Maximum Sequential Write Around 1300 ~ 1663 MB/s

Logical Blocks 500118192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]



Technical Specifications

Features ATA Security; TRIM; L1.2

SSD 256 GB 2280 M2 SATA-3 Self Encrypted OPAL2 Three Layer Cell Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 ATA-8, SATA 3.0

Maximum Sequential Read Around 530 ~ 560 MB/s
Maximum Sequential Write Around 500 ~ 530 MB/s

Logical Blocks 500118192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP

SSD 256 GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read Around 1500 ~ 1700 MB/s
Maximum Sequential Write Around 780 ~ 1300 MB/s

Logical Blocks 500118192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 2700 ~ 3400 MB/s
Maximum Sequential Write Around 1390 ~ 2956 MB/s

Technical Specifications

Logical Blocks 1000215215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 512 GB 2280 PCIe

NVMe Value

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC/QLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 1500 ~ 1700 MB/s
Maximum Sequential Write Around 860 ~ 1500 MB/s

Logical Blocks 1000215215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 512 GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read Around 2900 ~ 3400 MB/s
Maximum Sequential Write Around 1000 ~ 2500 MB/s

Logical Blocks 1000215216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP

Technical Specifications

NETWORKING/COMMUNICATIONS

intel® 9260
802.11a/b/g/n/ac (2 x 2)
Wi-Fi® and Bluetooth®
5.0 Combo ¹ Non-vPro

I----I® 0360

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r

IEEE 802.11v
Interoperability Wi-Fi certified

Frequency Band 802.11b/g/n

• 2.402 – 2.482 GHz 802.11a/n/ac

4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz

• 5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³
•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11iWAPI

•WAP

Network Architecture Ad-hoc (Peer to Peer)

Output Power²

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

802.11b: +18.5dBm minimum
802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
 802.11n HT40(2.4GHz): +14.5dBm minimum

• 802.11n HT20(5GHz): +15.5dBm minimum

Technical Specifications

802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum

• 802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption • Transmit mode: 2.0 W

•Receive mode: 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

•Radio disabled: 8 mW

Power Management ACPI compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac. MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8q

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF

LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy : 0~79 (1 MHz/CH)
Channels BLE : 0~39 (2 MHz/CH)



Technical Specifications

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps

BLE: 1 Mbps signaling data rate¹ 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface USB 2.0 compliant

Bluetooth Software

Supported

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Contifications**FCC (47 CER) Part 15C Section 15 347 8 15 347

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles
Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Laver

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Technical Specifications

802.11a/b/g/n/ac (2 x 2) Wireless LAN Standards

Wi-Fi® and Bluetooth®

4.2 Combo¹

IEEE 802.11a

IEEE 802.11b

IEEE 802.11a IEEE 802.11n

IEEE 802.11ac

Interoperability Wi-Fi® certified

Frequency Band 802.11b/g/n

• 2.402 - 2.482 GHz

802.11a/n

• 4.9 – 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

• 802.11b: 1, 2, 5.5, 11 Mbps **Data Rates**

> • 802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation **Direct Sequence Spread Spectrum**

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³ •IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

•WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +14dBm minimum

> • 802.11g: +12dBm minimum • 802.11a: +12dBm minimum

• 802.11n HT20(2.4GHz): +12dBm minimum

• 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum

802.11n HT40(5GHz): +10dBm minimum

• 802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

• Idle mode (PSP) 180 mW (WLAN Associated)

Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW



Technical Specifications

Power Management ACPI and PCI Express compliant power management 802.11 compliant

power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

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asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)



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Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

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LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

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- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® Wi-Fi® 65 AX200 + Wireless LAN Standards BT5 (802.11ax 2 x 2, nonvPro, supporting gigabit file transfer speeds) non-vPro

IEEE 802.11a

IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac

IEEE 802.11ax

Technical Specifications

IEEE 802.11d

IEEE 802.11e

IEEE 802.11h

IEEE 802.11i

IEEE 802.11k

IEEE 802.11r

IEEE 802.11v

Interoperability V

Wi-Fi® certified

Frequency Band 802.11b/g/n/ax

• 2.402 – 2.482 GHz 802.11a/n/ac/ax

• 4.9 – 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³
•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

•IEEE 802.11i

•WAPI

Network Architecture

Ad-hoc (Peer to Peer)

Models

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +18.5dBm minimum

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• 802.11a: +18.5dBm minimum

• 802.11n HT20(2.4GHz): +15.5dBm minimum

• 802.11n HT40(2.4GHz): +14.5dBm minimum

• 802.11n HT20(5GHz): +15.5dBm minimum

• 802.11n HT40(5GHz): +14.5dBm minimum

• 802.11ac VHT80(5GHz): +11.5dBm minimum

• 802.11ac VHT160(5GHz): +11.5dBm minimum

• 802.11ax HT40(2.4GHz): +10dBm minimum

Technical Specifications

• 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

• Connected Standby 10mW

• Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management 802.11 compliant

power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8q

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) **Channels** BLE: 0~39 (2 MHz/CH)



Technical Specifications

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹ 2.17 Mbps

BLE: 1 Mbps signaling data rate¹ 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 –Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.



Technical Specifications

Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

Intel® XMM™ 7360 LTE-Advanced CAT9¹ **Technology/Operating**

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to

450Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x

Thickness)

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. WWAN is an optional feature, requires factory configuration and separately purchased service contract. Check with service provider for coverage and availability in your area. 4G LTE not available on all products, in all regions.

Near Field Communications Controller (optional) Dimensions (L x W x H)

Module 25 mm by 10 mm by 2.0 mm

Chipset NPC300 System interface I2C



Technical Specifications

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD)

Mode(1)

ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation

ISO/IEC 14443 A

(PICC-VICC) Mode(1) ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer Raw RF Data Rates 106, 212, 424, 848 kbps

Operating temperature 0°C to 70°C

Storage temperature -20°C to 125°C

Humidity 10-90% operating

5-95% non-operating

Supply Operating voltage 4.35 to 5.25 Volts

I/O Voltage 1.8V or 3.3V

Power Consumption (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V) Mode Power Consumption, Typical

Polling 710.93 mW
Detected Test Tag Type 1 152.09 mW
Detected Test Tag Type 2 341.26 mW
Detected Test Tag Type 3 383.76 mW
Detected Test Tag Type 4 312.26 mW

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.

Realtek RTK8111EPH 10/100/1000 Integrated NIC **Connector** RJ-45

System Interface PCIe + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

Technical Specifications

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-

30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Power Consumption Cable Disconnection: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

Power Management ACPI compliant – multiple power modes

Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Security & Manageability RTK DASH support with appropriate RTK chipset components

POWER

AC Adapter 45 Watt nPFC Wall Mount USB type C Straight 1.8m C6NS

Dimensions Weight Input 62.0 x 62.0 x 28.5 mm unit: 220 g +/- 10 g

Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec: 5V: 81.5%

9V: 86.7% 10V: 87.5% 12V: 87.8%



Technical Specifications

Output

15V: 87.8%

20V: 87.8%

47 ~ 63Hz Input frequency range

Input AC current Max. 1.4 A at 90 Vac

Average Efficiency of 25%, 50%, 75%, 100% **Output power**

load condition with 115Vac/230Vac Spec:

DC output 5V: 81.5% Hold-up time 9V: 86.7%

Output current limit 10V: 87.5%

Connector Non-Standard C6

Environmental Design Operating temperature 32°F to 95°F (0° to 35°C)

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety CE Mark - full compliance with LVD and EMC directives Certifications

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m

Dimensions 95.0 x 40.0 x 26.5 mm Weight unit: 200 q +/- 10 q

Input **Input Efficiency** 87.74 % at 115 Vac and 88.4 % at 230Vac

> Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output 45W **Output power**

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector C6

Environmental Design Operating temperature 32°F to 95°F (0°to 35°C)

> Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% Storage Humidity 10% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

> Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200.000 hours at 25°C ambient condition.

Dimensions 95.0 x 40.0 x 26.5 mm

Technical Specifications

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m 2prong **Weight** unit: 200 g +/- 10 g

Input Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector C8

Environmental Design Operating temperature 32° to 95° F (0° to 35° C)

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions USB type C Straight 1.8 m Weight C6NS

Dimensions Weight Input 74 x 74 x 28.5 mm unit: 245 g +/- 10 g

Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output Output power 65W

 DC output
 5V/9V/10V/12V/15V/20V

 Hold-up time
 5ms at 115 Vac input

Output current limit <8.0A

Connector Non-Standard C6

Environmental Design Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage)

temperature

age) -4°F to 185°F (-20° to 85°C)

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 100,000 hours at 25°C ambient condition.

Technical Specifications

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5 mm New EM
 Dimensions
 102 x 55 x 30 mm

 Weight
 unit: 250 g +/- 10 g

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0 A

Connector C6

Environmental Design Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

 Altitude
 0 to 5,000 m

 Humidity
 20% to 95%

 Storage Humidity
 10% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m
 Dimensions
 90.0 x 51 x 28.5 mm

 Weight
 unit: 230 g +/- 10 g

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0 A

Connector C6

Environmental Design 4.5mm Barrel Type

Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

Technical Specifications

MTBF - over 200,000 hours at 25°C ambient condition.

Battery SS 3 Cell 50 WHr

Long Life -PL

Dimensions $(H \times W \times L)$

L 278.7 mm x W 76.3 mm x H 7.1 mm

Weight 193 +/- 10 g

Cells/Type 3cell Lithium-Ion Polymer cell / P604883A1

Voltage 11.55 V

Energy Amp-hour capacity 4.113 Ah/ 4.330 Ah

Watt-hour capacity 50 Wh

Temperature Operating (Charging) 0° to 50° C

Operating (Discharging) -10° to 60° C

Warranty based on system offering

Optional Travel Battery

Available

No

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

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Type	Description	Part #
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack	H1D24AA
	HP 17.3 Business Backpack	2SC67AA
	HP 15.6 Business Top Load	2SC66AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP UltraSlim Docking Station TAA US	E5C22AV
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 120W G2 TAA	2UK37AA
	HP TB Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP USB Travel Dock	TOK30AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP USB-C Universal Dock w/4.5mm Adapter - non-flash version	3DV65AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse to AMO	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2CE30AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA

Options and Accessories (sold separately and availability may vary by country)

-		
	HP UC Wireless Duo Headset	W3K09AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP HDMI to VGA	H4F02AA
Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
Storage	HP USB External DVDRW Drive	F2B56AA
Security	HP Docking Station Cable Lock	AU656AA
	HP Essential Combination Lock	TOY16AA
	HP Combination Lock	TOY15AA
	HP Keyed Cable lock	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Keyed Cable Lock	T1A64AA



Summary of Changes

Date of change:	te of change: Version History:		Description of change:
June 20, 2019	V1 to V2	Added	Environmental Section

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